NLAS3257A

Mux / Demux Analog Switch

The NLAS3257A Mux / Demux Analog Switch is an advanced high−speed single pole double throw (SPDT) analog switch in ultra−small footprint.

Features

- High Speed: t_{PD} = 0.25 ns (Max) @ V_{CC} = 4.5 V
- R_{ON}: 7.5 Ω, Typ @ V_{CC} = 4.2 V
- C_{ON}: 7.5 pF, Typ @ V_{CC} = 3.3 V
- V_{CC} Range: 1.65 V to 4.5 V
- Ultra−Small 1 x 1 mm Package
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- Mobile Phones, PDAs, Camera

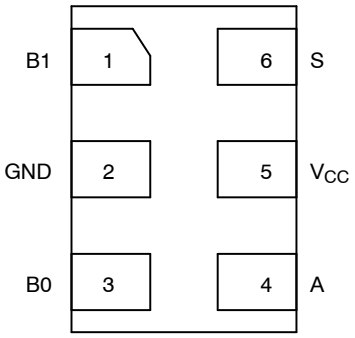

Figure 1. UDFN6
(Top View)

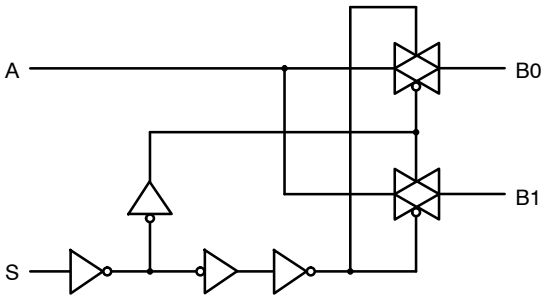

Figure 2. Logic Diagram

Function Table

Input S	Function
L	A = B0
H	A = B1

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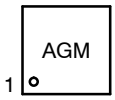
MARKING DIAGRAM

UDFN6
1.0 x 1.0
CASE 517EC



AG = Specific Device Code
M = Date Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

Table 1. MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage		−0.5 to +5.5	V
V_{IN}	Control Input Voltage (S Pin)		−0.5 to +5.5	V
$V_{I/O}$	Switch Input / Output Voltage (A, B0, B1 Pins)		−0.5 to V_{CC} + 0.5	V
I_{IK}	Control Pin DC Input Diode Current (S Pin)	V_{IN} < GND	−50	mA
I_{OK}	Switch I/O Port DC Diode Current (A, B0, B1 Pins)	$V_{I/O}$ < GND or $V_{I/O}$ > V_{CC}	±50	mA
I_O	On−State Switch Current		±128	mA
	Continuous Current Through V_{CC} or GND		±150	mA
I_{CC}	DC Supply Current per Supply Pin		±150	mA
I_{GND}	DC Ground Current per Ground Pin		±150	mA
T_{STG}	Storage Temperature Range		−65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
T_J	Junction Temperature Under Bias		150	°C
θ_{JA}	Thermal Resistance (Note 1)		466	°C/W
P_D	Power Dissipation in Still Air at 85°C (Note 1)		269	mW
MSL	Moisture Sensitivity		Level 1	
F_R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in	
V_{ESD}	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	>6000 >200 >2000	V
$I_{LATCHUP}$	Latchup Performance Above V_{CC} and Below GND at 85°C (Note 5)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm−by−1 inch, 2 ounce copper trace no air flow.
2. Tested to EIA/ JESD22−A114−A
3. Tested to EIA/ JESD22−A115−A
4. Tested to JESD22−C101−A
5. Tested to EIA / JESD78.

Table 2. RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V_{CC}	Positive DC Supply Voltage		1.65	4.5	V
V_I	Control Pin Input Voltage (S Pin)		0	4.5	V
$V_{I/O}$	Switch Input / Output Voltage (A, B0, B1 Pins)		0	V_{CC}	V
T_A	Operating Free−Air Temperature		−40	+85	°C
$\Delta t / \Delta V$	Input Transition Rise or Fall Rate	Control Input Switch I/O	0 0	20 DC	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Table 3. DC ELECTRICAL CHARACTERISTICS (Typical: T = 25°C, V_{CC} = 3.3 V)

Symbol	Parameter	Test Conditions	V_{CC} (V)	T_A = −40°C to +85°C			Unit
				Min	Typ	Max	
V_{IH}	Control Input, High Voltage (S Pin)		2.7 3.3 4.2	0.95 1.0 1.25			V
V_{IL}	Control Input, Low Voltage (S Pin)		2.7 3.3 4.2			0.3 0.4 0.5	V
I_{IN}	Control Input, Leakage Current (S Pin)	$0 \le V_{IN} \le V_{CC}$	1.65 – 4.5		±0.5	±1.0	μA
$I_{B0/B1\_OFF}$	Off State Leakage Current (B0/B1 Pins)	$V_{IN} = V_{IL}$ or V_{IH} V_{B0} and V_{B1} = 0.3 V V_A = 4 V	4.5		±20	±100	nA
I_{A_ON}	On State Leakage Current (A Pin)	$V_{IN} = V_{IL}$ or V_{IH} V_{B0} = 0.3 V or 4 V with V_{B1} = Floating or V_{B1} = 0.3 V or 4 V with V_{B0} = Floating V_A = 0.3 V or 4.0 V	4.5		±20	±100	nA
I_{Power_OFF}	Power Off Leakage Current (S Pin)	V_{IN} = 0 or 4.5 V	0			±100	nA
I_{CC}	Quiescent Supply Current (V_{CC} Pin)	$V_{IN} = V_{CC}$ or GND, $V_{IS} = V_{CC}$ or GND, I_{Load} = 0 A	1.65 – 4.5		0.1	1.0	μA
ΔI_{CC}	Additional Quiescent Supply Current (V_{CC} Pin)	$V_{IN} = V_{CC}$ or GND, $V_{IS} = V_{CC}$ or GND, I_{Load} = 0 A	3.3 4.2			2.0 3.0	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Table 4. ON RESISTANCE (Typical: T = 25°C)

Symbol	Parameter	Test Conditions	V_{CC} (V)	T_A = −40°C to +85°C			Unit
				Min	Typ	Max	
R_{ON}	ON−Resistance	I_{ON} = 8 mA, V_{IS} = 0 V to V_{CC}	2.7 3.3 4.2		9.3 8.7 7.5		Ω
R_{FLAT}	ON−Resistance Flatness	I_{ON} = 8 mA, V_{IS} = 0 V to V_{CC}	2.7 3.3 4.2		3.6 3.3 2.9		Ω
ΔR_{ON}	Delta ON− Resistance	I_{ON} = 8 mA, V_{IS} = 0 V to V_{CC}	2.7 3.3 4.2		0.8 0.7 0.5		Ω

AC ELECTRICAL CHARACTERISTICS

Table 5. TIMING/FREQUENCY (Typical: T = 25°C, V_{CC} = 3.3 V, R_L = 50 Ω, C_L = 5 pF, f = 1 MHz)

Symbol	Parameter	Test Condition	V_{CC} (V)	T_A = −40°C to +85°C			Unit
				Min	Typ	Max	
t_{PD}	Propagation Delay, A to Bn or Bn to A		1.65 – 4.5			0.25	ns
t_{ON}	Turn−ON Time	(See Figures 4 and 5)	1.65 – 4.5			35	ns
t_{OFF}	Turn−OFF Time	(See Figures 4 and 5)	1.65 – 4.5			25	ns
t_{BBM}	Break−Before−Make Time	(See Figure 3)	1.65 – 4.5	2.0			ns
BW	−3 dB Bandwidth	C_L = 5 pF	1.65 – 4.5		900		MHz

Table 6. ISOLATION (Typical: T = 25°C, V_{CC} = 3.3 V, R_L = 50 Ω, C_L = 5 pF)

Symbol	Parameter	Test Condition	V_{CC} (V)	T_A = −40°C to +85°C			Unit
				Min	Typ	Max	
O_{IRR}	OFF−Isolation	f = 240 MHz (See Figure 6)	1.65 – 4.5		−21		dB
X_{TALK}	Non−Adjacent Channel Crosstalk	f = 240 MHz	1.65 – 4.5		−21		dB

Table 7. CAPACITANCE (Typical: T = 25°C, V_{CC} = 3.3 V, f = 1 MHz)

Symbol	Parameter	Test Condition	T_A = −40°C to +85°C			Unit
			Min	Typ	Max	
C_{IN}	Control Input Capacitance	S pin			2.0	pF
C_{ON}	ON Capacitance	Switch ON A to B0 A to B1			7.5	pF
C_{OFF}	OFF Capacitance	Switch OFF B0 OFF B1 OFF			2.5	pF

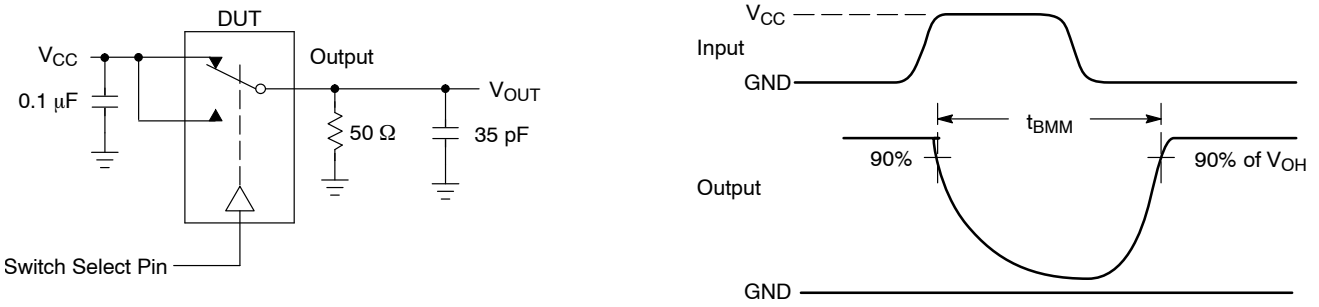


Figure 3. t_{BBM} (Time Break−Before−Make)

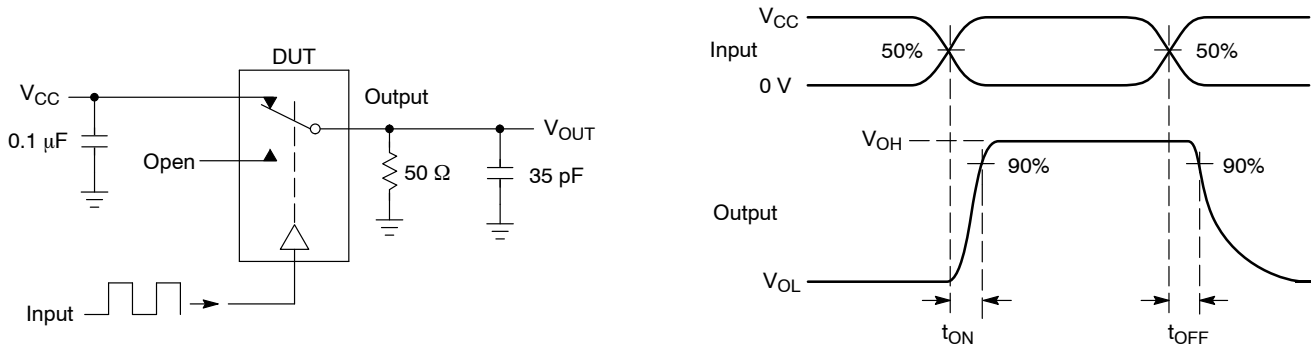


Figure 4. t_{ON}/t_{OFF}

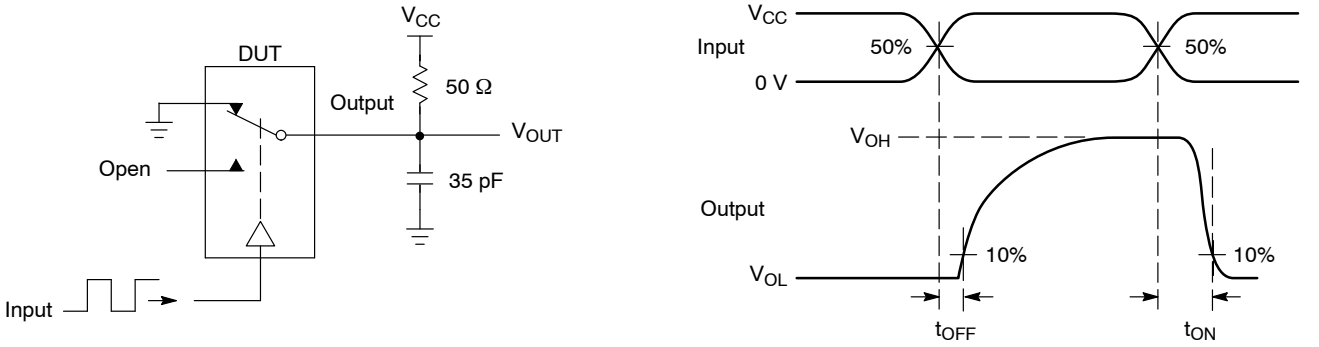
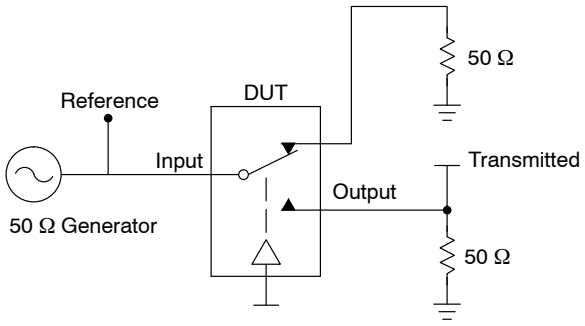


Figure 5. t_{ON}/t_{OFF}



Channel switch control/s test socket is normalized. Off isolation is measured across an off channel. On loss is the bandwidth of an On switch. V_{ISO}, Bandwidth and V_{ONL} are independent of the input signal direction.

V_{ISO} = Off Channel Isolation = 20 Log $\left(\frac{V_{OUT}}{V_{IN}}\right)$ for V_{IN} at 100 kHz

V_{ONL} = On Channel Loss = 20 Log $\left(\frac{V_{OUT}}{V_{IN}}\right)$ for V_{IN} at 100 kHz to 50 MHz

Bandwidth (BW) = the frequency 3 dB below V_{ONL}
V_{CT} = Use V_{ISO} setup and test to all other switch analog input/outputs terminated with 50 Ω

Figure 6. Off Channel Isolation/On Channel Loss (BW)/Crosstalk (On Channel to Off Channel)/V_{ONL}

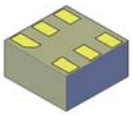
DEVICE ORDERING INFORMATION

Device	Package	Shipping†
NLAS3257AMU3TCG	UDFN6 – 1.0 x 1.0, 0.35P (Pb–Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

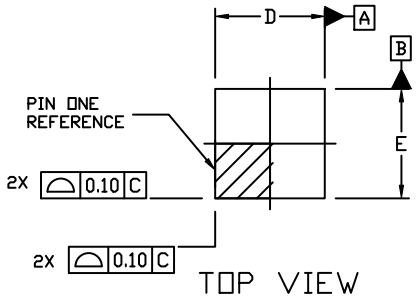
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

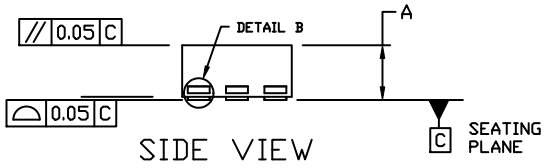
ON Semiconductor®

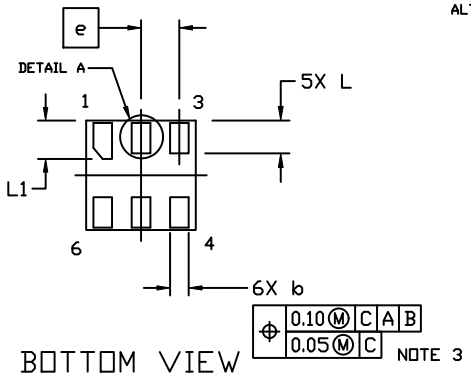


UDFN6 1x1, 0.35P
CASE 517EC
ISSUE O

DATE 09 NOV 2018

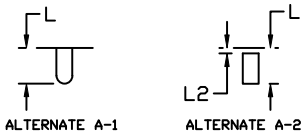


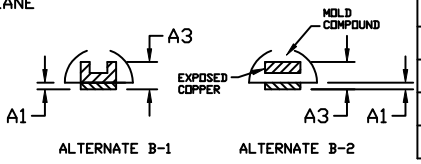




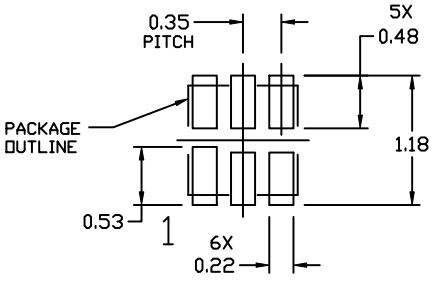
NOTES:

1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO THE PLATED TERMINALS AND IS MEASURED BETWEEN 0.15 AND 0.20 FROM THE TERMINAL TIPS.
4. PACKAGE DIMENSIONS EXCUSIVE OF BURRS AND MOLD FLASH.





DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.45	0.50	0.55
A1	0.00	0.025	0.05
A3		0.13 REF	
b	0.12	0.17	0.22
D	0.90	1.00	1.10
E	0.90	1.00	1.10
e		0.35 BSC	
L	0.25	0.30	0.35
L1	0.30	0.35	0.40
L2	---	---	0.10



* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	**98AON00214H**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.	
DESCRIPTION:	**UDFN6 1x1, 0.35P**		**PAGE 1 OF 1**

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
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For additional information, please contact your local Sales Representative

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